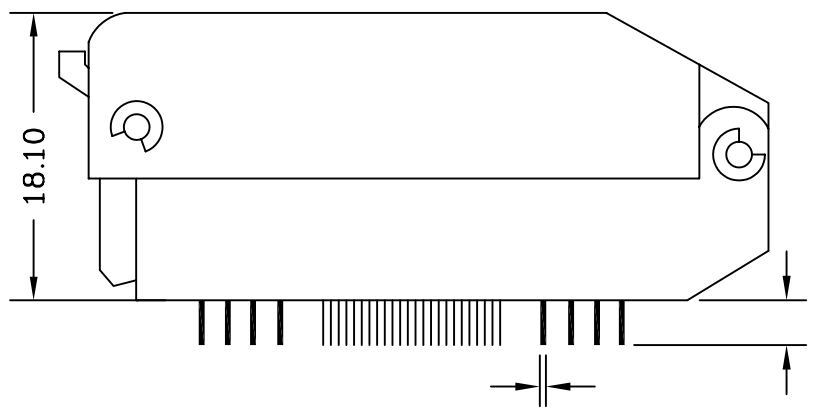
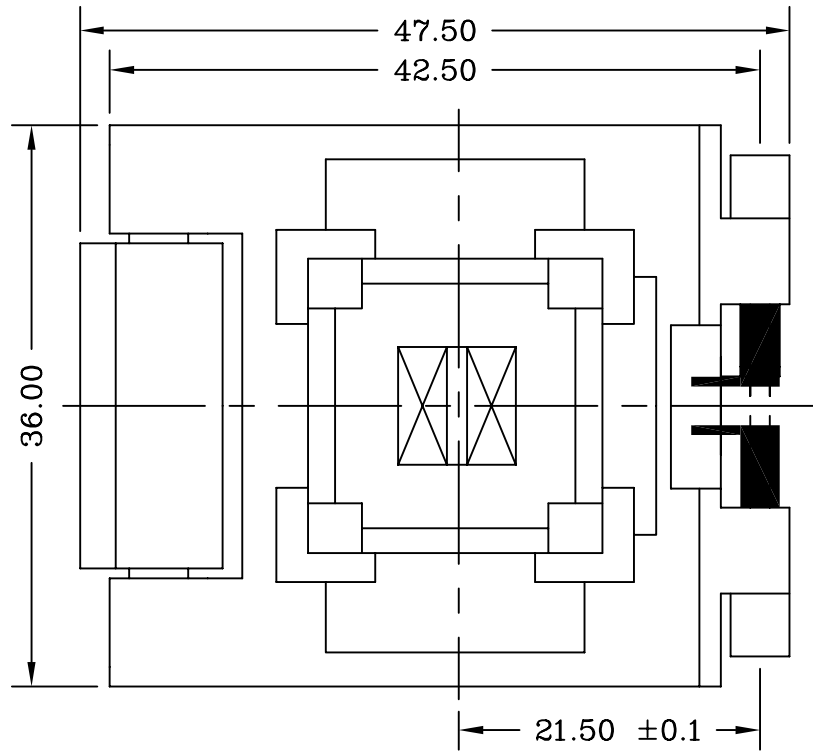


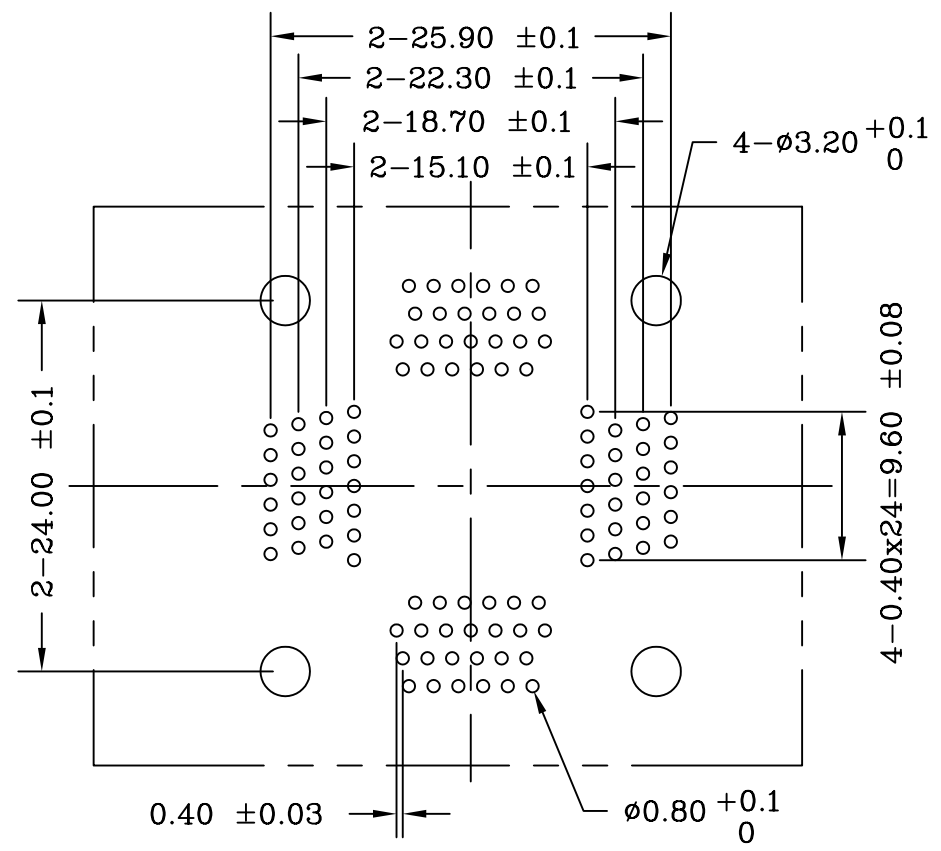
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	02/05/07	H.N.

SKT2859

RECOMMENDED PCB LAYOUT  
AS SEEN FROM TOP OF SOCKET

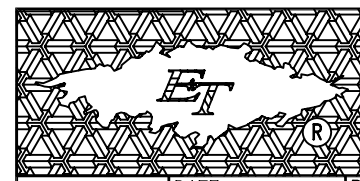


CONTACT TAILS  
0.45 X 0.20



**SPECIFICATIONS:**

INSULATION RESISTANCE: 500mΩ OR MORE AT 100VDC  
 DIELECTRIC WITHSTANDING VOLTAGE: 100VAC FOR ONE MINUTE  
 CONTACT RESISTANCE: 30mΩ OR LESS AT 10mA, 20mV OR LESS  
 OPERATING TEMPERATURE: -55°C TO +170°C  
 CONTACT FORCE: 25g~200g WITHIN CONTACT TRAVEL DISTANCE;  
 BETWEEN 0.3~1.0 FOR EACH INDIVIDUAL CONTACT.



**Emulation Technology, Inc.**  
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F  
Santa Clara, Ca 95051  
TEL:(408)982-0660  
FAX:(408)982-0664

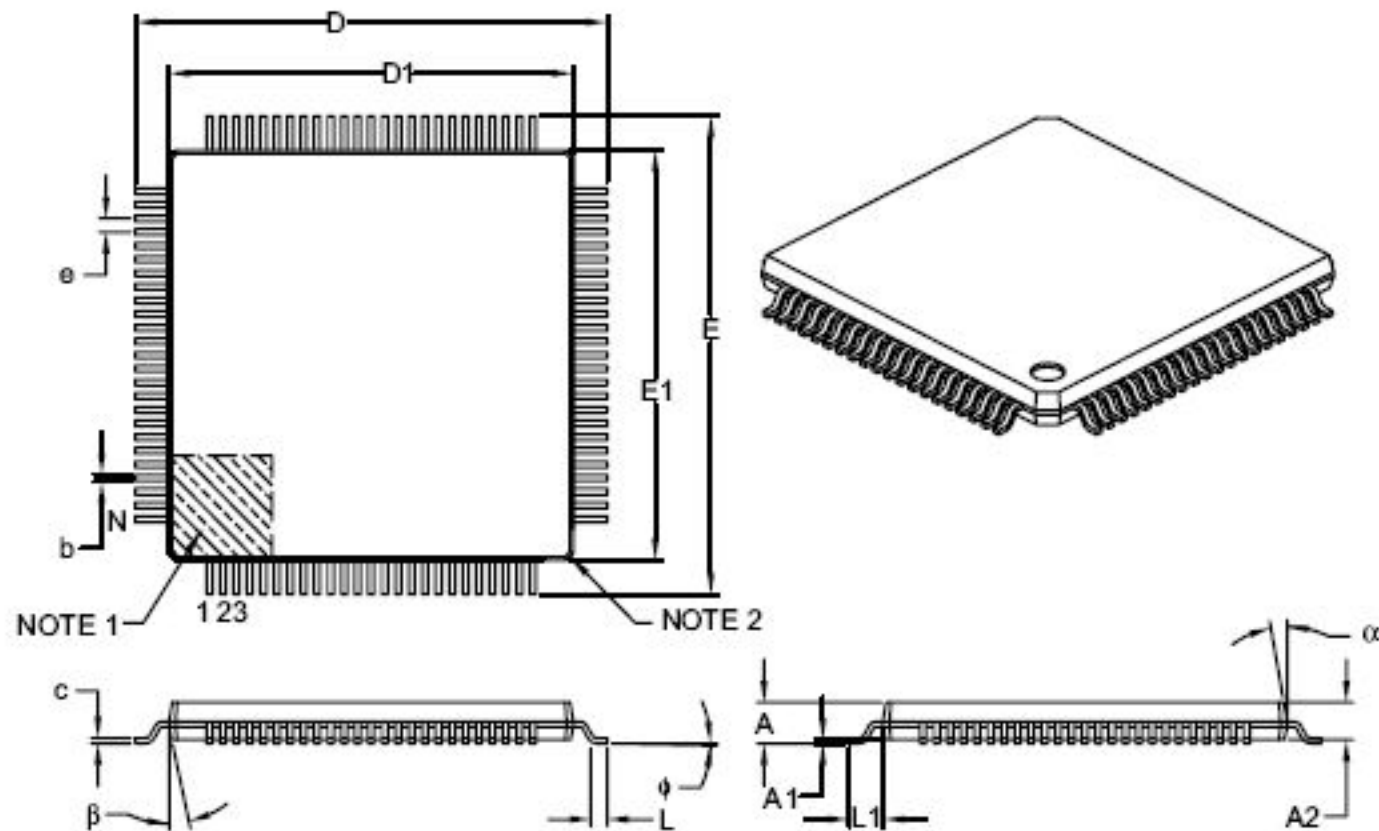
PACKAGE SPECIFICATIONS	
PIN COUNT	≡ 100
LEAD PITCH	≡ 0.40mm
PACKAGE SIZE	≡ 12.00mm SQ
TIP TO TIP	≡ 14.00mm SQ

UNLESS OTHERWISE SPECIFIED:  
DIMENSIONS ARE IN MILLIMETERS  
GENERAL TOLERANCES: ±0.3

SHEET: 1 OF 2	DATE: 02/05/07	REVISION: A	<b>ASSEMBLY DRAWING</b>
CHECKED:	DRAWN: H.N.	ITEM: S-QFP-00-100-T	DESCRIPTION: S-QFP-00-100-T
Scale N/A	DO NOT SCALE DRAWING		

## 100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm Footprint [TQFP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	$\phi$	0°	3.5°	7°
Overall Width	E	14.00 BSC		
Overall Length	D	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Molded Package Length	D1	12.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	$\alpha$	11°	12°	13°
Mold Draft Angle Bottom	$\beta$	11°	12°	13°

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B